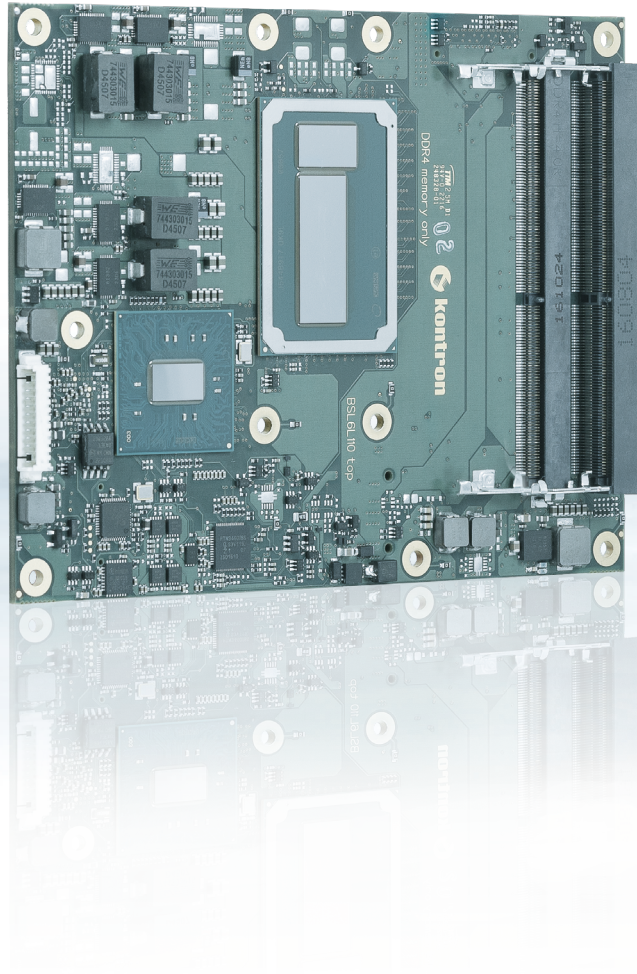


COMe-bSL6



COM Express® basic Type 6
with 6th Gen Intel® Core™ /Xeon® processors

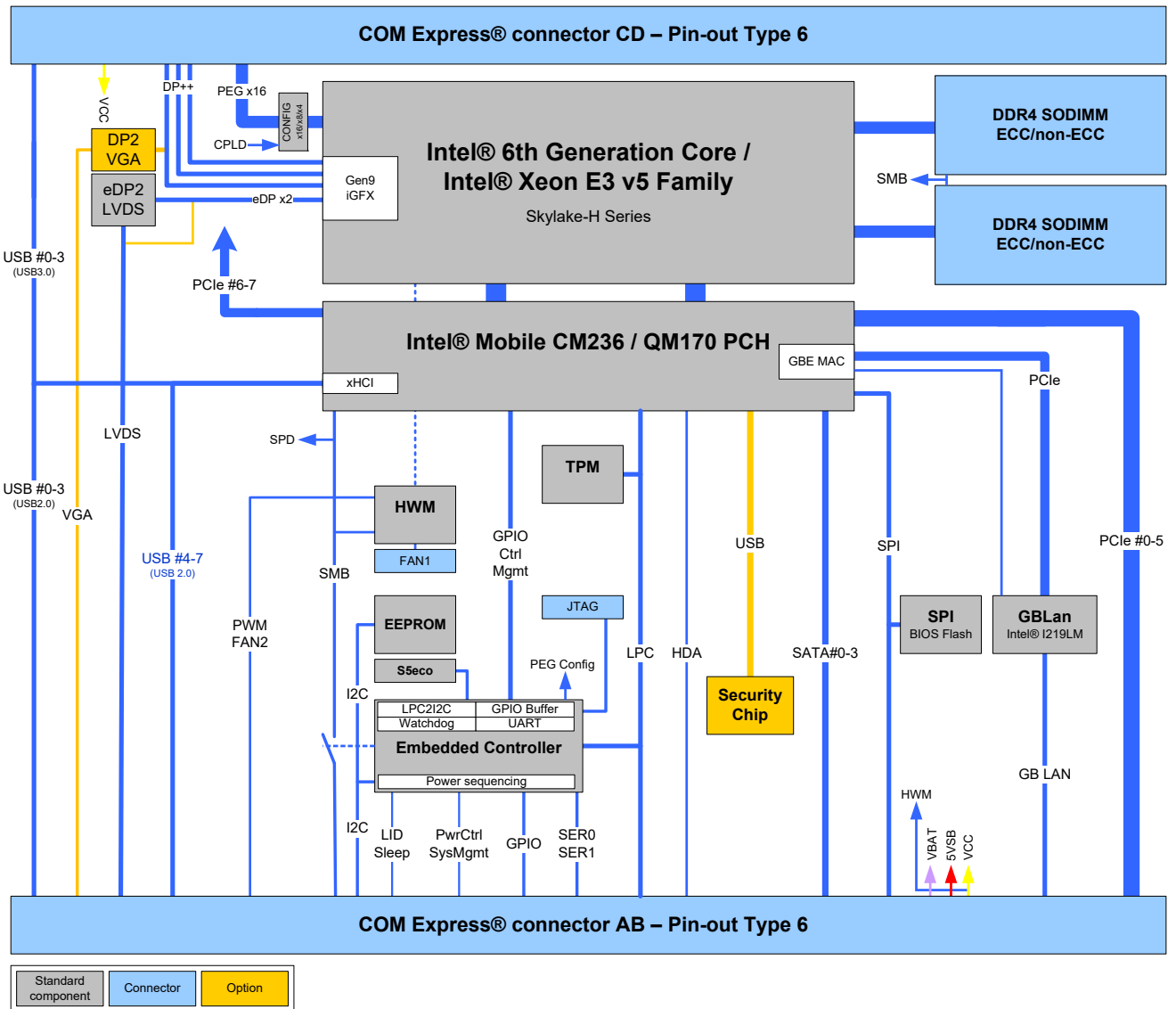
- ▶ Intel® 6th Gen Core™ series/Xeon® E3 v5 family with CM236/QM170 PCH
- ▶ Up to 32 GByte DDR4 non-ECC/ECC memory

POSSIBILITIES START HERE

► TECHNICAL INFORMATION

COMPLIANCE	COM Express® basic, Pin-out Type 6
DIMENSIONS (H x W)	125 x 95 mm
CPU	Intel® Xeon® E3-1515M, Intel® Xeon® E3-1505M, Intel® Xeon® E3-1505L, Intel® Core™ i7-6820EQ, Intel® Core™ i7-6822EQ, Intel® Core™ i5-6440EQ, Intel® Core™ i5-6442EQ, Intel® Core™ i3-6100E, Intel® Core™ i3-6102E, Intel® Celeron™ G3900E, Intel® Celeron™ G3902E
CHIPSET	Intel® Mobile CM236 / Intel® Mobile QM170 (Core™ i5 & Core™ i7)
MAIN MEMORY	2x DDR4-2133 SO-DIMM up to 2x 16 GByte (non-ECC/ECC)
GRAPHICS CONTROLLER	Intel® Iris™ Pro Graphics P580 (GT4e), Intel® HD Graphics P530 (GT2), Intel® HD Graphics P510 (GT1)
ETHERNET CONTROLLER	Intel® I219LM
ETHERNET	10/100/1000 MBit Ethernet
HARD DISK	4x SATA 6Gb/s
FLASH ONBOARD	-
PCI EXPRESS® SUPPORT	8x PCIe x1, 1x PEG x16
PANEL SIGNAL	DDI1: DP++, DDI2: DP++, DDI3: DP++, VGA: -, LVDS: Dual Channel 18/24bit
USB	4x USB 3.0 (incl. USB 2.0) + 4x USB 2.0
SERIAL	2x serial interface (RX/TX only)
AUDIO	Intel® High Definition Audio
COMMON FEATURES	SPI, LPC, SMB, Fast I ² C, Staged Watchdog, RTC, MARS
BIOS	AMI Aptio V
HUMIDITY	93 % relative Humidity at 40° C, non-condensing (according to IEC 60068-2-78)
ON REQUEST	vPRO (AMT/TXT/AES Support), eDP instead of LVDS, VGA, Intel® Mobile HM170 Chipset, Security Chip
POWER MANAGEMENT	ACPI 6.0, S5 Eco
POWER SUPPLY	8.5 V - 20 V Wide Range, Single Supply Power
SPECIAL FEATURES	POSCAP capacitors, Trusted Platform Module TPM 2.0, 4k Resolutions, Flexible PEG lane configuration by Setup Option
OPERATING SYSTEM	Windows® 10, Windows® 8.1, Windows® 7, WES7, Linux, VxWorks

► BLOCK DIAGRAM



► GLOBAL HEADQUARTERS

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